

Yuxiu Li

List of Publications by Year in descending order

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Version: 2024-02-01

11
papers

303
citations

1684188

5
h-index

1474206

9
g-index

11
all docs

11
docs citations

11
times ranked

363
citing authors

#	ARTICLE	IF	CITATIONS
1	Numerical simulation on heat transfer of supercritical carbon dioxide in helical coiled channels under one-side heating. <i>International Journal of Thermal Sciences</i> , 2022, 174, 107391.	4.9	5
2	Instabilities of a freely moving spherical particle in a Newtonian fluid: Direct Numerical Simulation. <i>International Journal of Chemical Reactor Engineering</i> , 2021, 19, 699-715.	1.1	1
3	Heat Transfer and Thermocapillary Flow of a Double-Emulsion Droplet Heated Using an Infrared Laser by the Photothermal Effect: a Numerical Study. <i>Microgravity Science and Technology</i> , 2021, 33, 1.	1.4	4
4	Nonuniform heat transfer of supercritical pressure carbon dioxide under turbulent cooling condition in circular tubes at various inclination angles. <i>Nuclear Engineering and Design</i> , 2019, 352, 110153.	1.7	12
5	Wettability Transition of a Liquid Droplet on Solid Surface With Nanoscale Inverted Triangular Grooves. , 2019, , .		1
6	Inertial particle focusing and spacing control in microfluidic devices. <i>Microfluidics and Nanofluidics</i> , 2018, 22, 1.	2.2	11
7	Molecular dynamics simulation of nanoscale liquid flows. <i>Microfluidics and Nanofluidics</i> , 2010, 9, 1011-1031.	2.2	134
8	Bubble Dynamics and Boiling Heat Transfer in Microsystems. , 2008, , .		0
9	Boundary conditions at the solid-liquid surface over the multiscale channel size from nanometer to micron. <i>International Journal of Heat and Mass Transfer</i> , 2007, 50, 2571-2581.	4.8	49
10	A New Criterion Number for the Boundary Conditions at the Solid/Liquid Interface in Nanoscale. <i>Nanoscale and Microscale Thermophysical Engineering</i> , 2006, 10, 109-141.	2.6	4
11	Transient flow pattern based microscale boiling heat transfer mechanisms. <i>Journal of Micromechanics and Microengineering</i> , 2005, 15, 1344-1361.	2.6	82